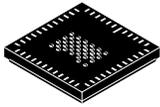


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

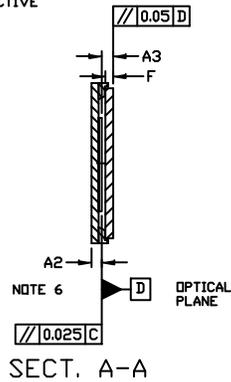
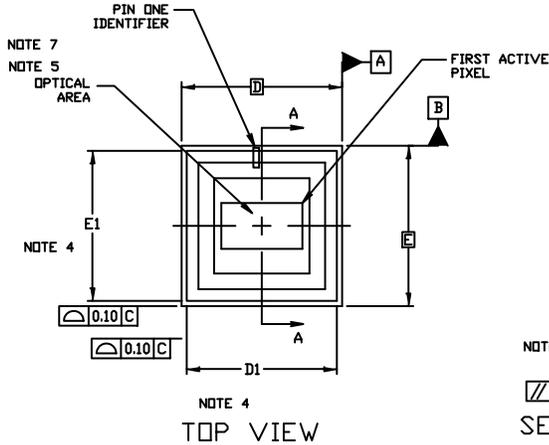


### PLCC48 11.43x11.43 (HiSPi)

#### CASE 776AQ

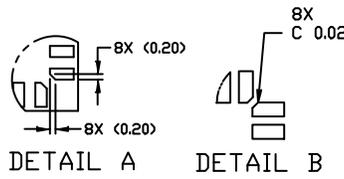
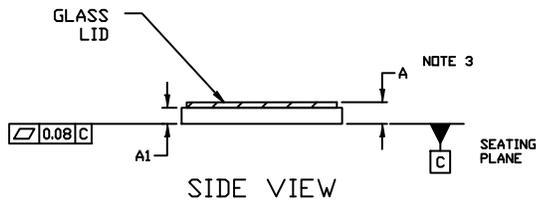
#### ISSUE E

DATE 20 NOV 2017

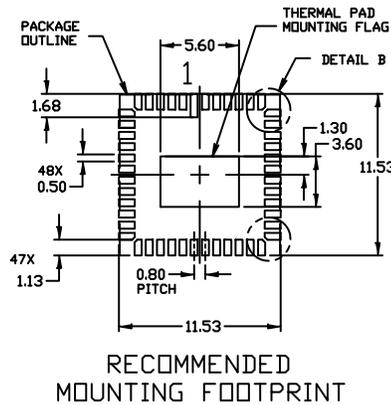
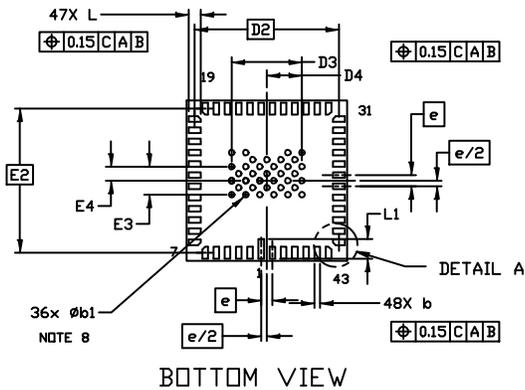


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.
5. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE D AND E WILL BE 0.5°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATA SHEET FOR TOTAL ARRAY AND FIRST PIXEL DEFINITIONS.
6. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
7. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X= 275 MICRONS, Y= 0 MICRONS ±75 MICRONS.
8. SOLDER MASK OPENINGS FOR THERMAL CONNECTION PADS.



DIM	MILLIMETERS	
	MIN.	MAX.
A	1.36	1.71
A1	1.15	REF
A2	0.65	0.80
A3	0.71	0.91
b	0.35	0.45
b1	0.40	REF
D	11.43	BSC
D1	10.65	10.75
D2	10.28	BSC
D3	5.00	REF
D4	2.00	REF
E	11.43	BSC
E1	10.65	10.75
E2	10.28	BSC
E3	2.50	REF
E4	1.00	REF
e	0.80	BSC
F	0.50	0.60
L	0.80	0.90
L1	1.35	1.45



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DESCRIPTION:	PLCC48 11.43X11.43 (HiSPi)	PAGE 1 OF 2

